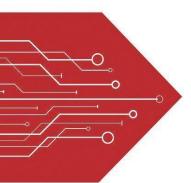
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Broduct data speet

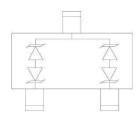














SOT-23

Features

- 300 Watts peak pulse power (tp = $8/20\mu$ s)
- Transient protection for high speed data lines to IEC 61000-4-2 (ESD) ±30kV (air), ±30kV(contact) IEC 61000-4-4 (EFT) 40A (5/50ns)
- Working voltages: 3,3V,5V,12V,15V,24V
- Protects two bidirectional line
- Low operating and clamping voltages
- Solid-state silicon avalanche technology

Applications

- Notebooks, Desktops, Servers and Video Graphics Cards
- **USB Power & Data Line Protection**
- Monitors and Flat Panel Displays
- I²C Bus Protection
- Portable Instrumentation
- Set Top Box

Electrical Characteristics@ Ta=25[°]Cunless otherwise

| P/N | V _{RWM} (V) | V _B (V) | I _⊤ (mA) | V _C @1A (V) | | /c V) | I _R (μΑ) | C _⊤ (pF) |
|---------------|-------------------------|--------------------|------------------------|---------------------------|--------|----------|------------------------|------------------------|
| 17/1 | (max.) | (min.) | , , | (max.) | (max.) | (@A) | (max.) | (max.) |
| ESD3V3L2BT-MS | 3.3 | 4 | 1 | 7.0 | 14 | 18 | 1 | 100 |
| ESD5V0L2BT-MS | 5 | 6 | 1 | 9.8 | 18 | 13 | 1 | 75 |
| ESD12VL2BT-MS | 12 | 13.3 | 1 | 19 | 32 | 5 | 1 | 20 |
| ESD15VL2BT-MS | 15 | 16.7 | 1 | 24 | 38 | 5 | 1 | 20 |
| ESD24VL2BT-MS | 24 | 26.7 | 1 | 43 | 52 | 5 | 1 | 35 |

Maximum Rating @ Ta=25 [℃] unless otherwisespecified

| Symbol | Parameter | Ratings | Units |
|------------------|--------------------------------|-------------|------------|
| P _{PK} | Peak Pulse Power (tp = 8/20µs) | 300 | Watts |
| TL | Lead Soldering Temperature | 260(10sec.) | $^{\circ}$ |
| TJ | Operating Temperature | -55 to +125 | $^{\circ}$ |
| T _{STG} | Storage Temperature | -55 to +150 | $^{\circ}$ |

ESDXXXL2BT-MS HF

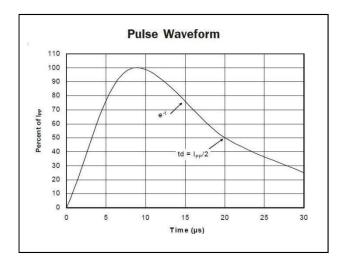


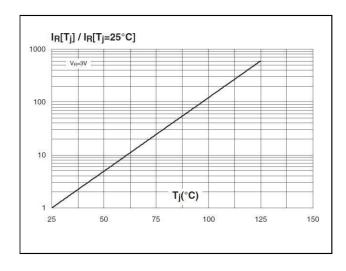


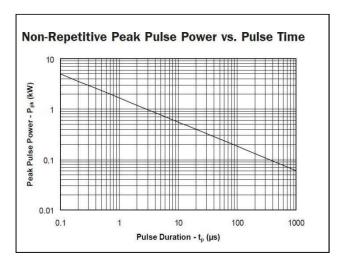


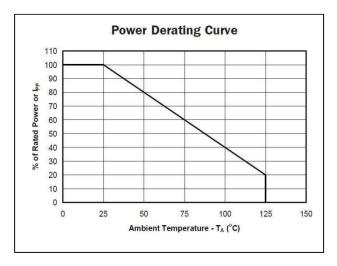


Typical Characteristics@ Ta=25℃unless otherwise specified



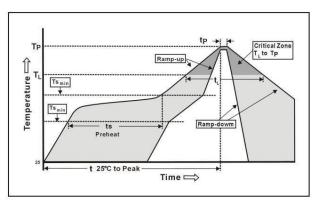






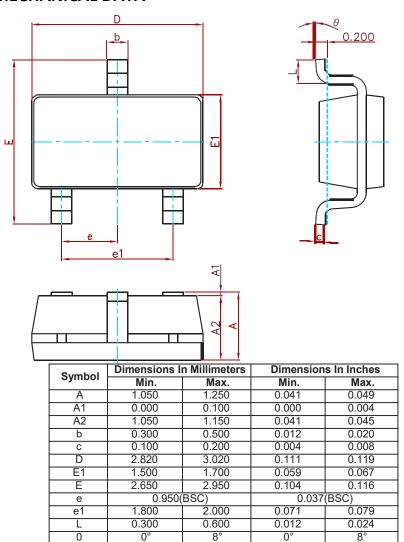
Soldering Parameters

| Reflow Condition | | Fb — Free assembly | |
|---|---|--------------------|--|
| Pre Heat | -Temperature Min (T _{s(Min)}) | 150°C | |
| | -Temperature Max (T _{s(Max)}) | 200°C | |
| | -Time (Min to max) (t _s) | 60 - 180 secs | |
| Average ramp up rate (Liquidus) Temp (T,) to peak | | 3°C/second Max | |
| T _{s (Max)} to T _L - Ramp-up Rate | | 3°C/second Max | |
| Reflow | -Temperature (T _L) (Liquidus) | 217°C | |
| | -Temperature (t _L) | 60 - 150 seconds | |
| Peak Temperature (T _p) | | 250+0/-5 °C | |
| Time within 5°C of actual peak Temperature (t _p) | | 20 – 40 seconds | |
| Ramp-dowm Rate | | 6°C/second Max | |
| Time 25°C to peak Temperature (T _p) | | 8 minutes Max. | |
| Do not exceed | | 260°C | |

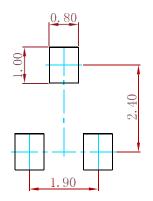




PACKAGE MECHANICAL DATA



Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

| P/N | PKG | QTY |
|---------------|--------|------|
| ESDXXXL2BT-MS | SOT-23 | 3000 |



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